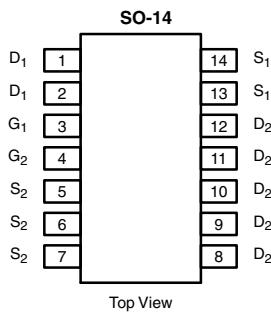


## Dual N-Channel 20 V (D-S) MOSFET with Schottky Diode

PRODUCT SUMMARY				
	V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)
Channel-1	20	0.0085 at V <sub>GS</sub> = 10 V	14.8	8.1
		0.0115 at V <sub>GS</sub> = 4.5 V	12.8	
Channel-2	20	0.0070 at V <sub>GS</sub> = 10 V	22	8.4
		0.0095 at V <sub>GS</sub> = 4.5 V	18.9	

SCHOTTKY PRODUCT SUMMARY		
V <sub>DS</sub> (V)	V <sub>SD</sub> (V) Diode Forward Voltage	I <sub>F</sub> (A)
20	0.55 V at 2.5 A	2



### FEATURES

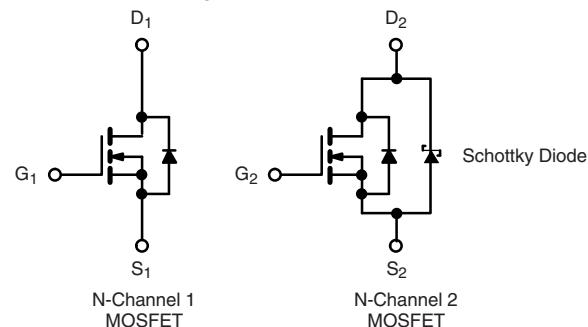
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC



RoHS  
COMPLIANT  
HALOGEN  
FREE

### APPLICATIONS

- DC/DC Converters, Synchronous Buck Converters
  - Game Stations
  - Notebook PC Logic



Ordering Information: Si4340DDY-T1-GE3 (Lead (Pb)-free and Halogen-free)

### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)

Parameter	Symbol	Channel-1	Channel-2	Unit
Drain-Source Voltage	V <sub>DS</sub>	20	± 20	V
Gate-Source Voltage	V <sub>GS</sub>			
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C	I <sub>D</sub>	14.8	A
	T <sub>C</sub> = 70 °C		11.8	
	T <sub>A</sub> = 25 °C		12.1 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C		9.7 <sup>b, c</sup>	
Pulsed Drain Current (t = 300 μs)	I <sub>DM</sub>	50	60	
Source-Drain Current Diode Current	T <sub>C</sub> = 25 °C	I <sub>S</sub>	2.5	
	T <sub>A</sub> = 25 °C		1.7 <sup>b, c</sup>	
Single Pulse Avalanche Current	I <sub>AS</sub>	15		mJ
Single Pulse Avalanche Energy	E <sub>AS</sub>	11.25		
Maximum Power Dissipation	T <sub>C</sub> = 25 °C	P <sub>D</sub>	3	W
	T <sub>C</sub> = 70 °C		1.9	
	T <sub>A</sub> = 25 °C		2 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C		1.3 <sup>b, c</sup>	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C

### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Channel-1		Channel-2		Unit
		Typ.	Max.	Typ.	Max.	
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 10 s	R <sub>thJA</sub>	53	62.5	35	42
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	35	42	18	23

Notes:

- a. Based on T<sub>C</sub> = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under steady state conditions for channel 1 is 110 °C/W and channel 2 is 87 °C/W.

**SPECIFICATIONS** ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
<b>Static</b>							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	Ch-1	20			
		$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	Ch-2	20			
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = 250 \mu\text{A}$	Ch-1		20		
		$I_D = 25 \text{ mA}$	Ch-2		22		
$V_{GS(\text{th})}$ Temperature Coefficient	$\Delta V_{GS(\text{th})}/T_J$	$I_D = 250 \mu\text{A}$	Ch-1		- 4.4		
		$I_D = 25 \text{ mA}$	Ch-2		- 4.6		
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	Ch-1	1		2.5	
		$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	Ch-2	1		2.5	
Gate-Source Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	Ch-1		100		
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	Ch-2		100		
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	Ch-1		1		
		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	Ch-2		100		
		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 85^\circ\text{C}$	Ch-1		15		
		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 85^\circ\text{C}$	Ch-2		10 000		
On-State Drain Current <sup>b</sup>	$I_{D(\text{on})}$	$V_{DS} \geq 5 \text{ V}, V_{GS} = 10 \text{ V}$	Ch-1	20			
		$V_{DS} \geq 5 \text{ V}, V_{GS} = 10 \text{ V}$	Ch-2	30			
Drain-Source On-State Resistance <sup>b</sup>	$R_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}, I_D = 11.5 \text{ A}$	Ch-1		0.0065	0.0085	
		$V_{GS} = 10 \text{ V}, I_D = 15.2 \text{ A}$	Ch-2		0.0060	0.0070	
		$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$	Ch-1		0.0091	0.0115	
		$V_{GS} = 4.5 \text{ V}, I_D = 14 \text{ A}$	Ch-2		0.0077	0.0095	
Forward Transconductance <sup>b</sup>	$g_{fs}$	$V_{DS} = 10 \text{ V}, I_D = 11.5 \text{ A}$	Ch-1		28		
		$V_{DS} = 10 \text{ V}, I_D = 15.2 \text{ A}$	Ch-2		44		
<b>Dynamic<sup>a</sup></b>							
Input Capacitance	$C_{iss}$	Channel-1 $V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	Ch-1		862		
			Ch-2		956		
Output Capacitance	$C_{oss}$		Ch-1		280		
			Ch-2		363		
Reverse Transfer Capacitance	$C_{rss}$	Channel-2 $V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	Ch-1		116		
			Ch-2		120		
Total Gate Charge	$Q_g$	$V_{DS} = 10 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 12 \text{ A}$	Ch-1		17.4	26	
		$V_{DS} = 10 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 12 \text{ A}$	Ch-2		17.8	27	
Gate-Source Charge	$Q_{gs}$	Channel-1 $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 12 \text{ A}$	Ch-1		8.1	12.5	
			Ch-2		8.4	12.5	
		Channel-2 $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 12 \text{ A}$	Ch-1		2.2		
			Ch-2		2.6		
Gate-Drain Charge	$Q_{gd}$	$f = 1 \text{ MHz}$	Ch-1		2.4		
			Ch-2		2.5		
Gate Resistance	$R_g$		Ch-1		2.2	4.4	
			Ch-2		2.6	5.2	

## Notes:

a. Guaranteed by design, not subject to production testing.  
 b. Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .

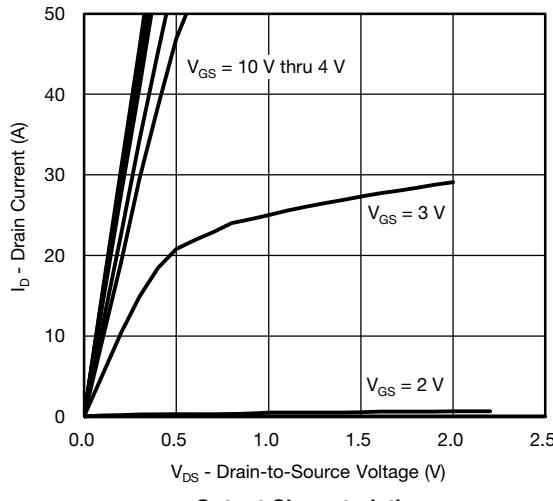
<b>SPECIFICATIONS</b> ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)							
Parameter	Symbol	Test Conditions			Min.	Typ.	Max.
<b>Dynamic<sup>a</sup></b>							
Turn-On Delay Time	$t_{d(on)}$	Channel-1 $V_{DD} = 10\text{ V}$ , $R_L = 1\Omega$ $I_D \approx 10\text{ A}$ , $V_{GEN} = 4.5\text{ V}$ , $R_g = 1\Omega$	Ch-1		18	35	ns
Rise Time	$t_r$		Ch-2		20	40	
Turn-Off Delay Time	$t_{d(off)}$		Ch-1		37	70	
Fall Time	$t_f$		Ch-2		34	65	
Turn-On Delay Time	$t_{d(on)}$		Ch-1		19	35	
Rise Time	$t_r$		Ch-2		21	40	
Turn-Off Delay Time	$t_{d(off)}$		Ch-1		10	20	
Fall Time	$t_f$		Ch-2		10	20	
Turn-On Delay Time	$t_{d(on)}$	Channel-1 $V_{DD} = 10\text{ V}$ , $R_L = 1\Omega$ $I_D \approx 10\text{ A}$ , $V_{GEN} = 10\text{ V}$ , $R_g = 1\Omega$	Ch-1		9	18	
Rise Time	$t_r$		Ch-2		9	18	
Turn-Off Delay Time	$t_{d(off)}$		Ch-1		13	26	
Fall Time	$t_f$		Ch-2		13	26	
Turn-On Delay Time	$t_{d(on)}$		Ch-1		16	32	
Rise Time	$t_r$		Ch-2		15	30	
Turn-Off Delay Time	$t_{d(off)}$		Ch-1		8	16	
Fall Time	$t_f$		Ch-2		8	16	
<b>Drain-Source Body Diode Characteristics</b>							
Continuous Source-Drain Diode Current	$I_S$	$T_C = 25^\circ\text{C}$	Ch-1			2.5	A
Pulse Diode Forward Current <sup>a</sup>	$I_{SM}$		Ch-2			4.5	
Body Diode Voltage	$V_{SD}$		Ch-1			50	
Body Diode Reverse Recovery Time	$t_{rr}$		Ch-2			60	
Body Diode Reverse Recovery Charge	$Q_{rr}$		Ch-1		0.76	1.2	V
Reverse Recovery Fall Time	$t_a$		Ch-2		0.43	0.55	
Reverse Recovery Rise Time	$t_b$		Ch-1		18	36	ns
			Ch-2		18	36	
			Ch-1		7	14	nC
			Ch-2		7	14	
			Ch-1		8		ns
			Ch-2		10		
			Ch-1		9		ns
			Ch-2		9		

## Notes:

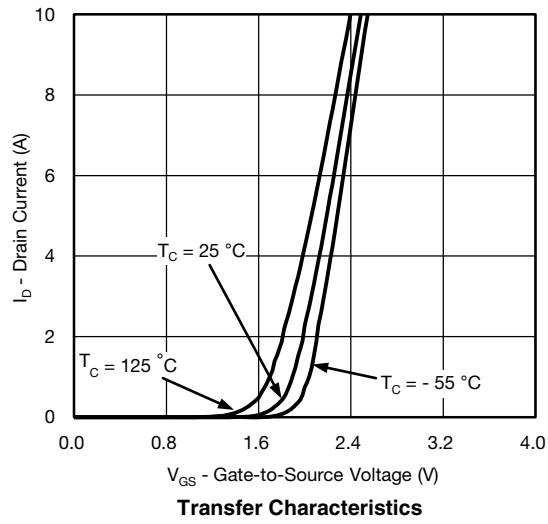
- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

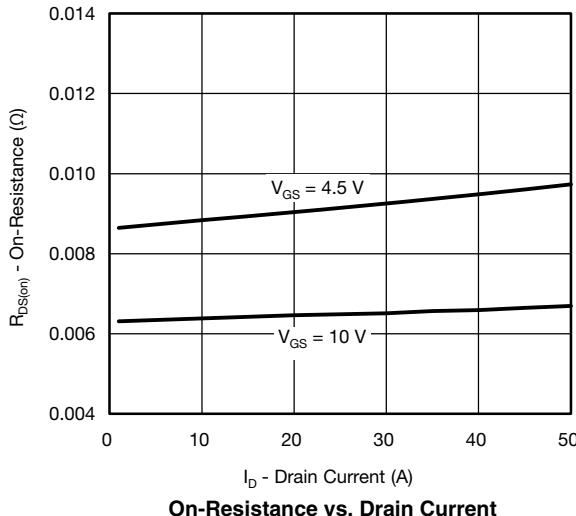
## CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



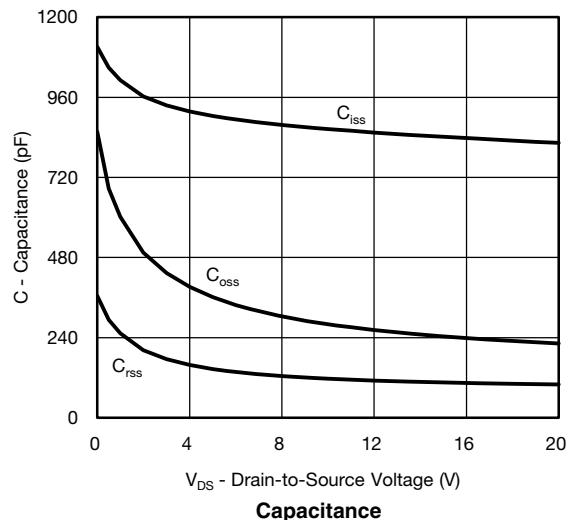
Output Characteristics



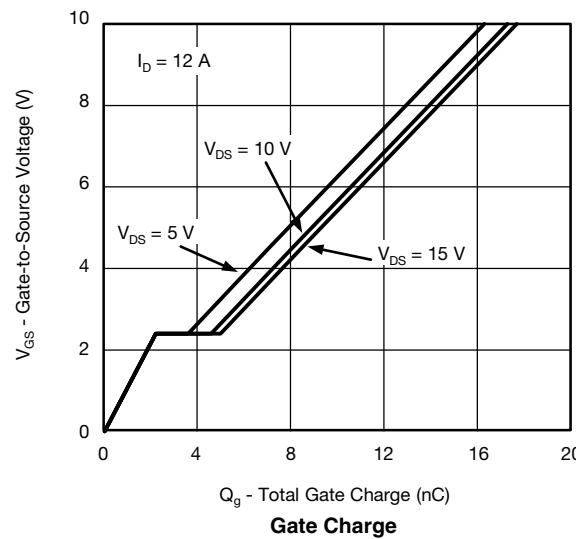
Transfer Characteristics



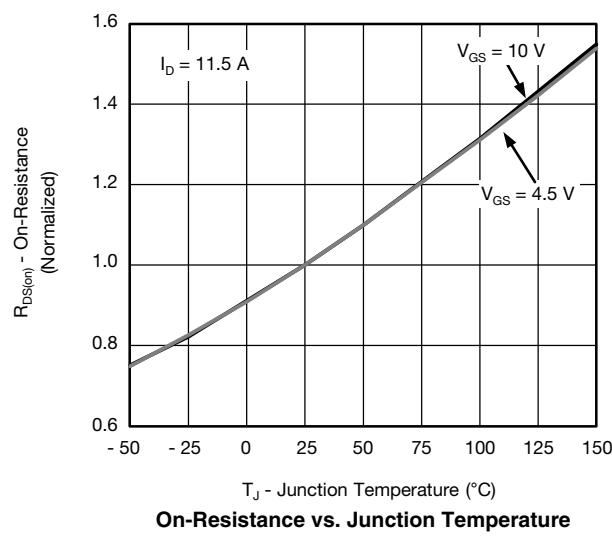
On-Resistance vs. Drain Current



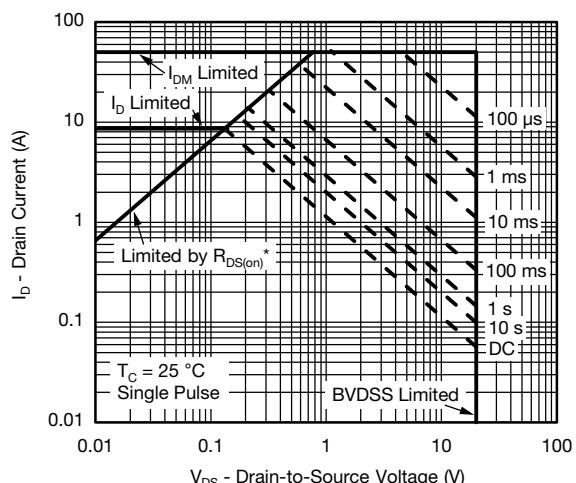
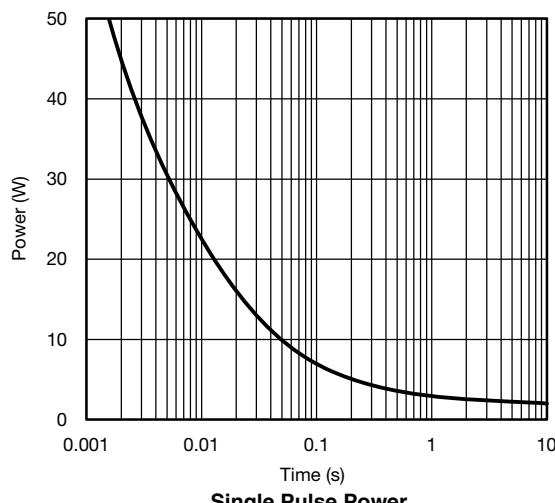
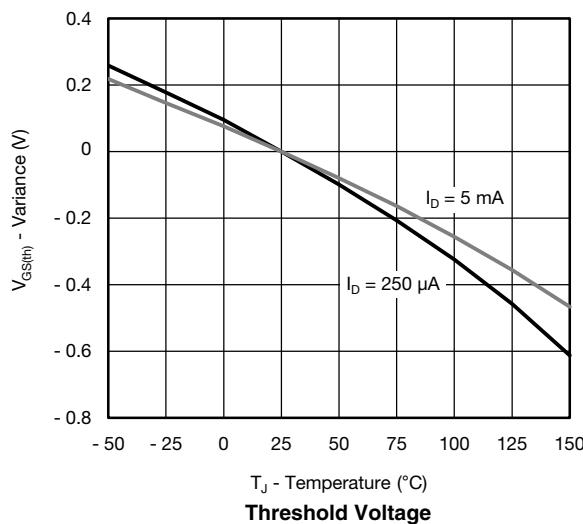
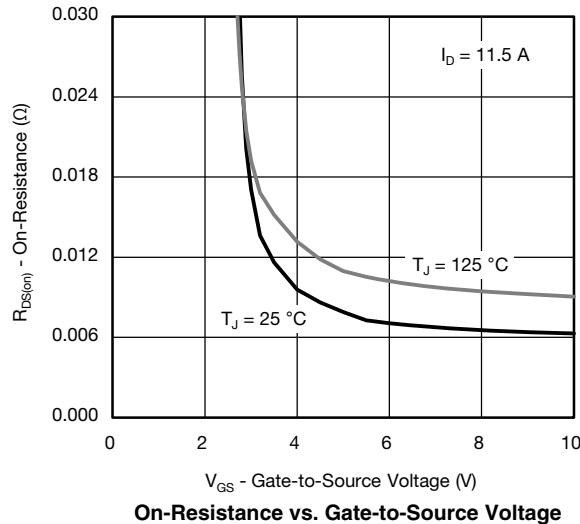
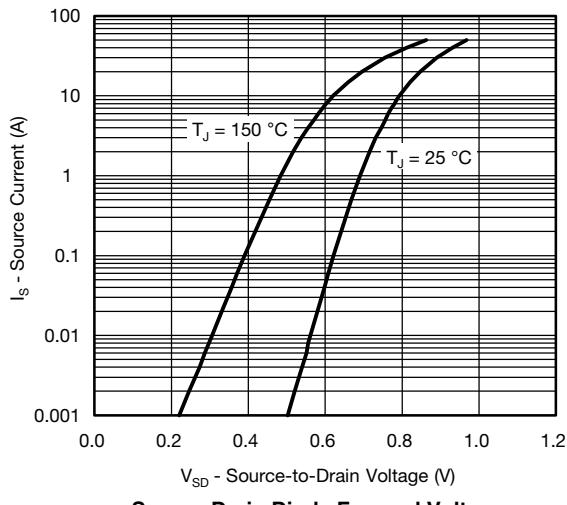
Capacitance



Gate Charge

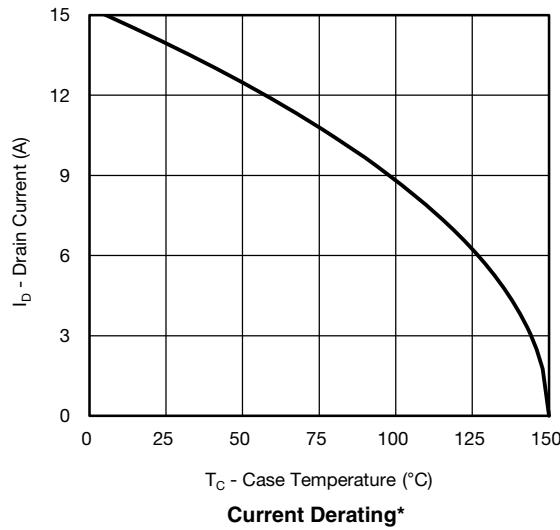


On-Resistance vs. Junction Temperature

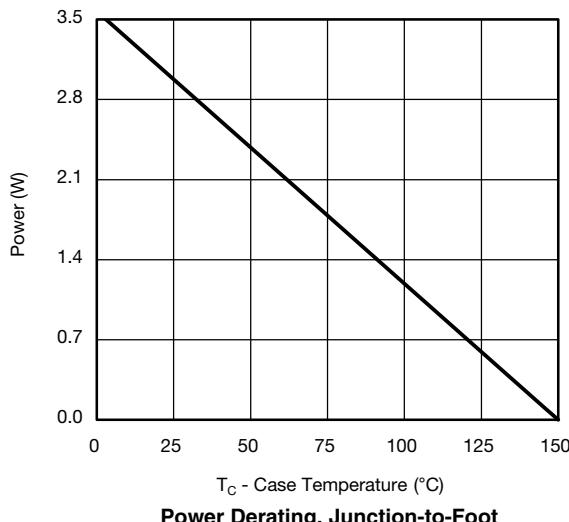
**CHANNEL-1 TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)


\*  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

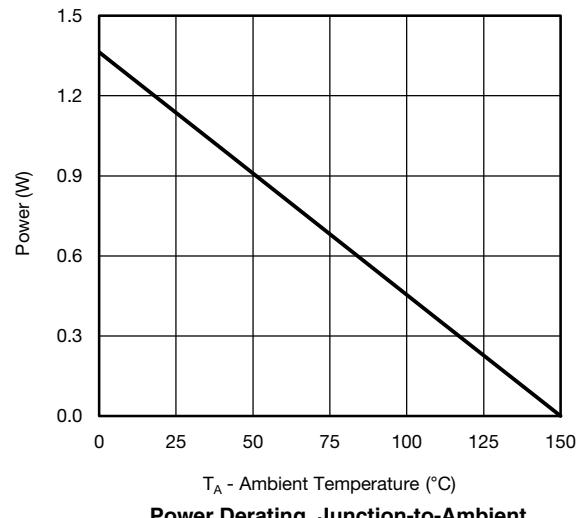
## CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating\*

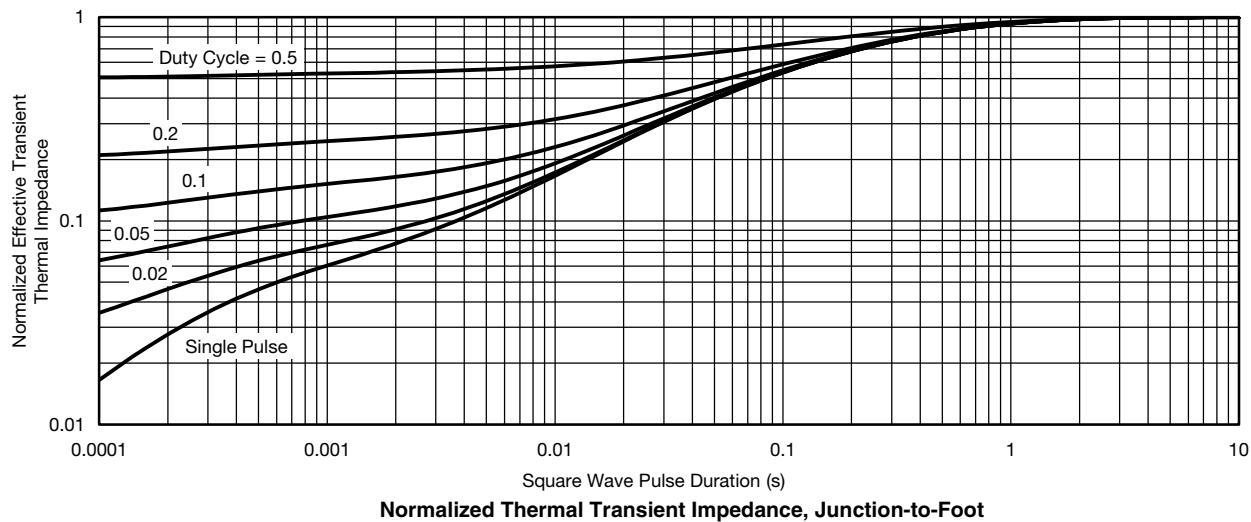
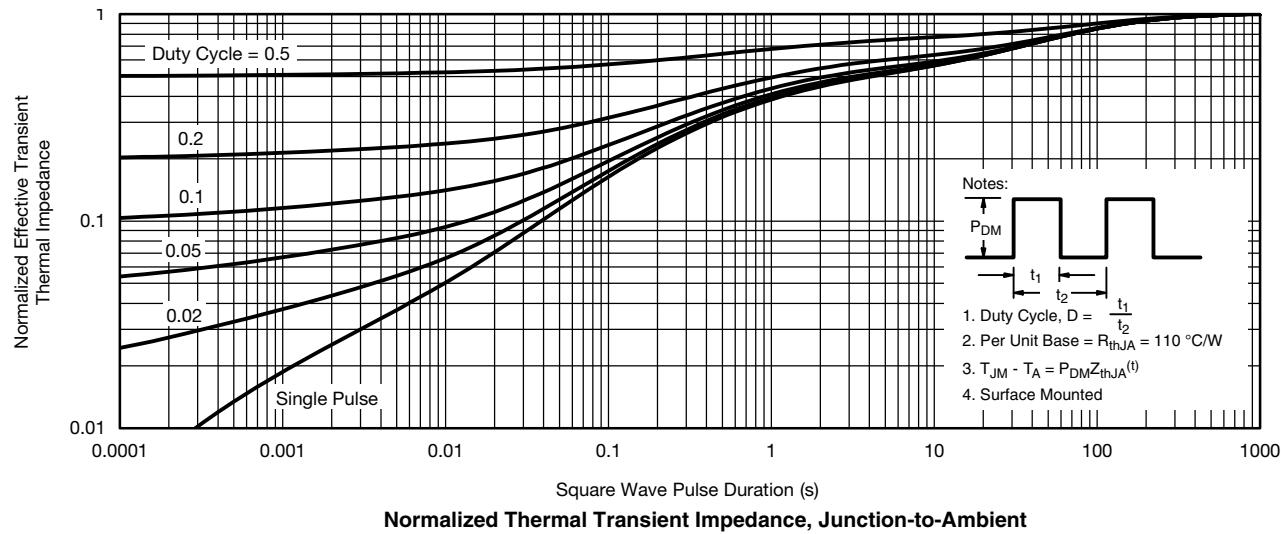


Power Derating, Junction-to-Foot

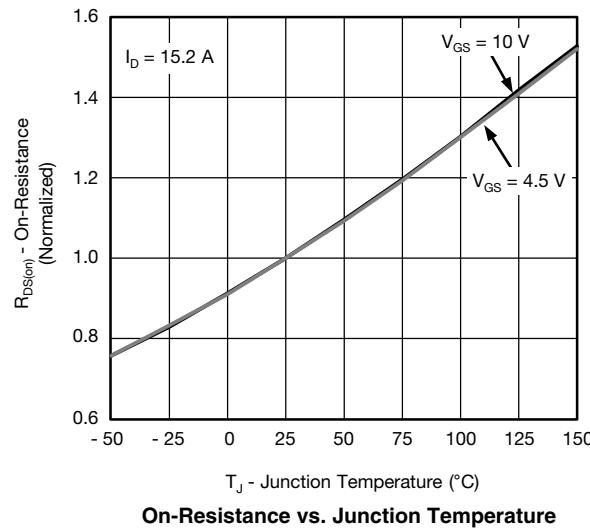
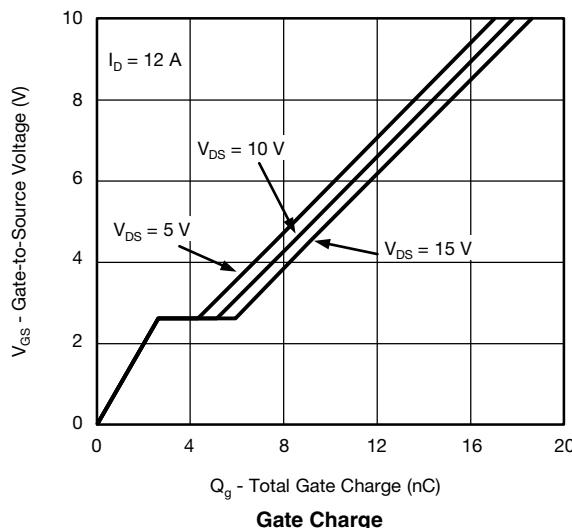
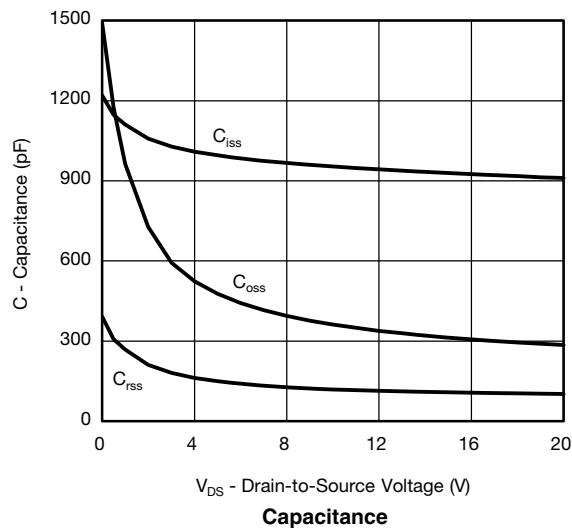
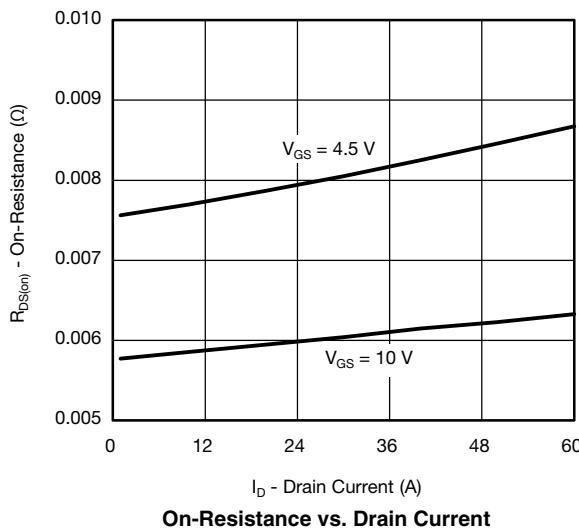
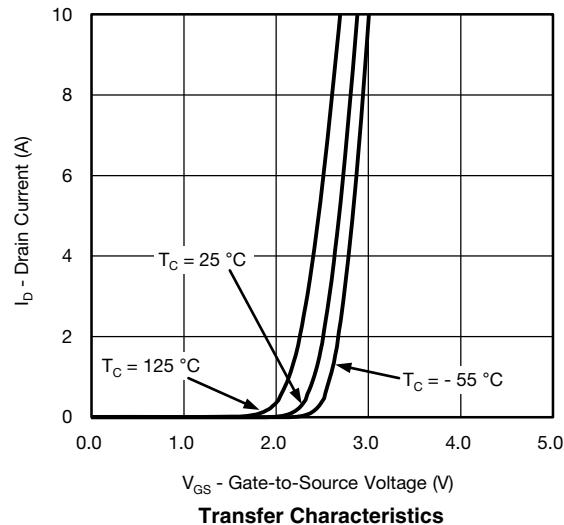
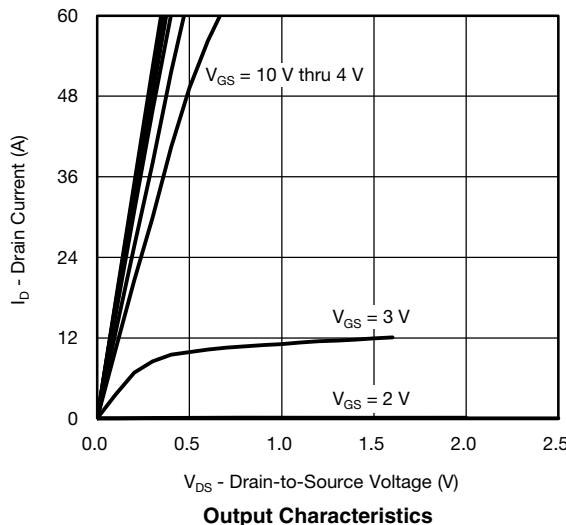


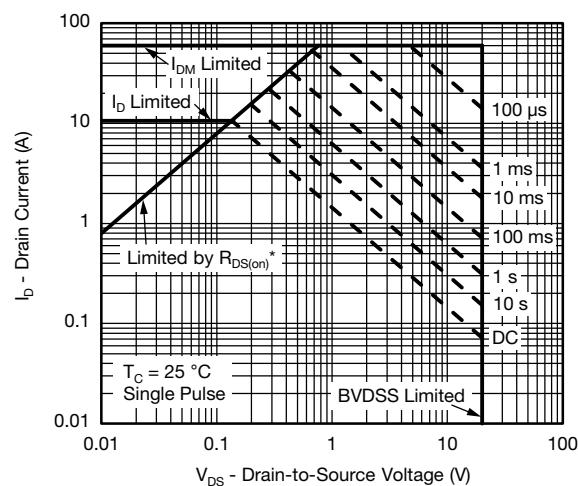
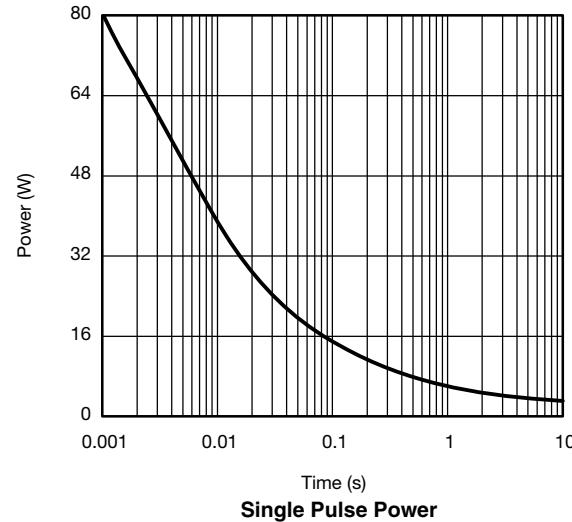
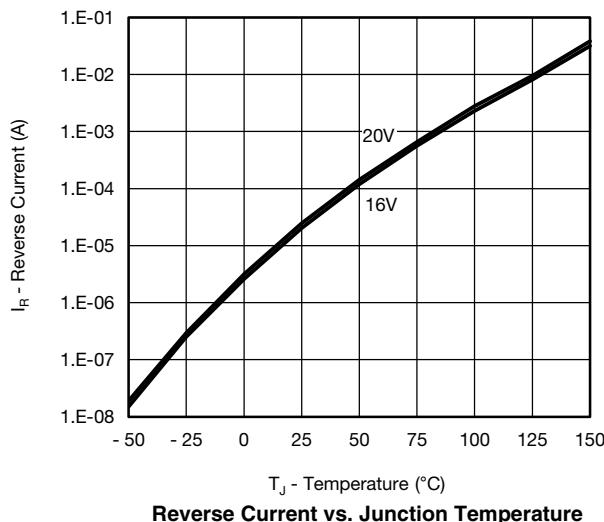
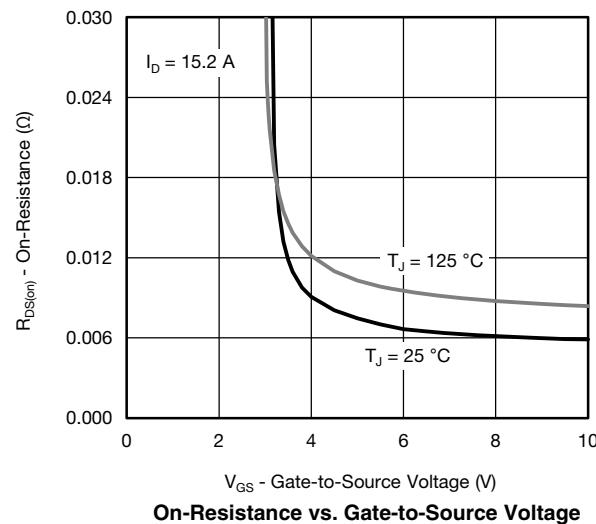
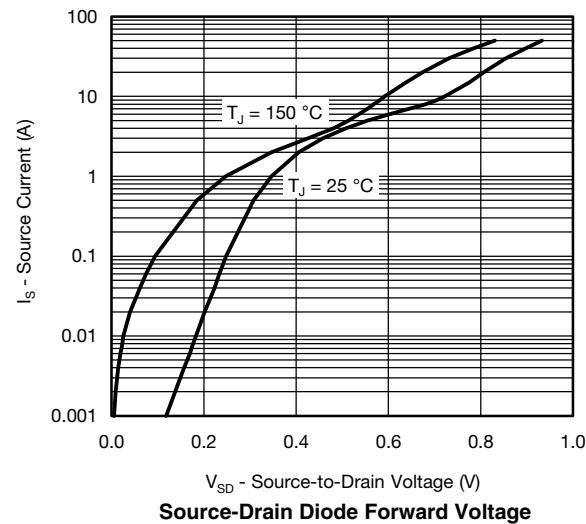
Power Derating, Junction-to-Ambient

\* The power dissipation  $P_D$  is based on  $T_{J(\max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

**CHANNEL-1 TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)


## CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

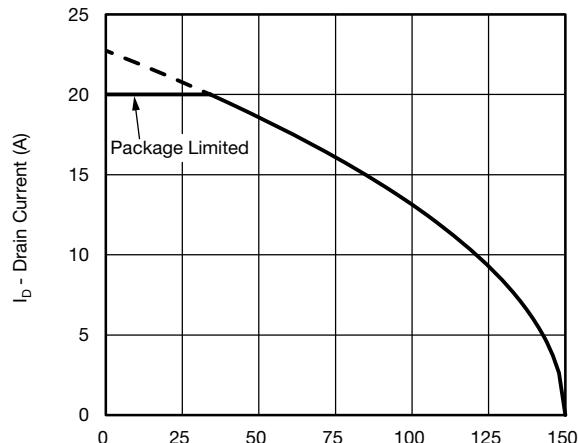


**CHANNEL-2 TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)


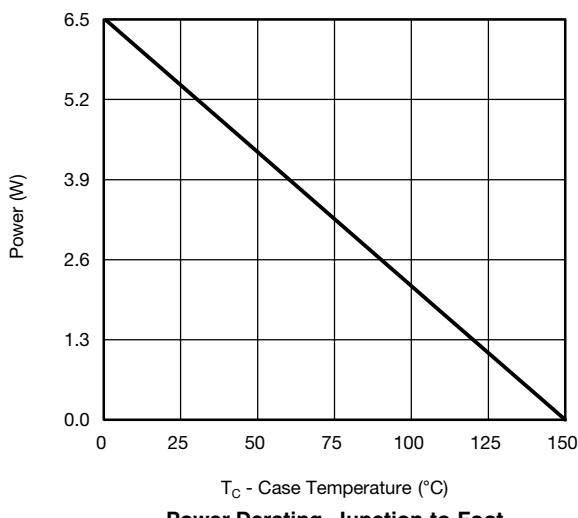
\*  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

**Safe Operating Area, Junction-to-Ambient**

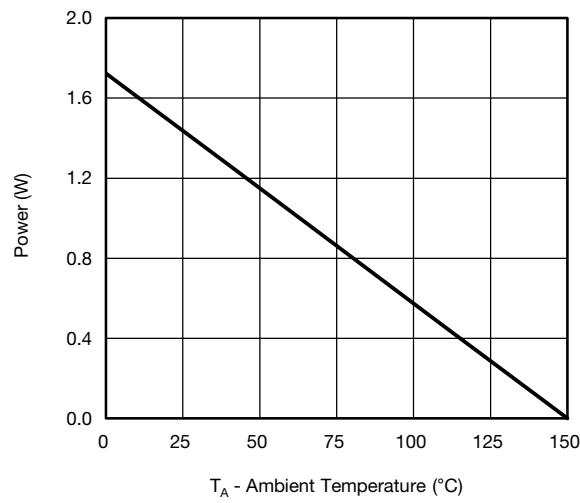
## CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

 $T_C$  - Case Temperature (°C)

Current Derating\*

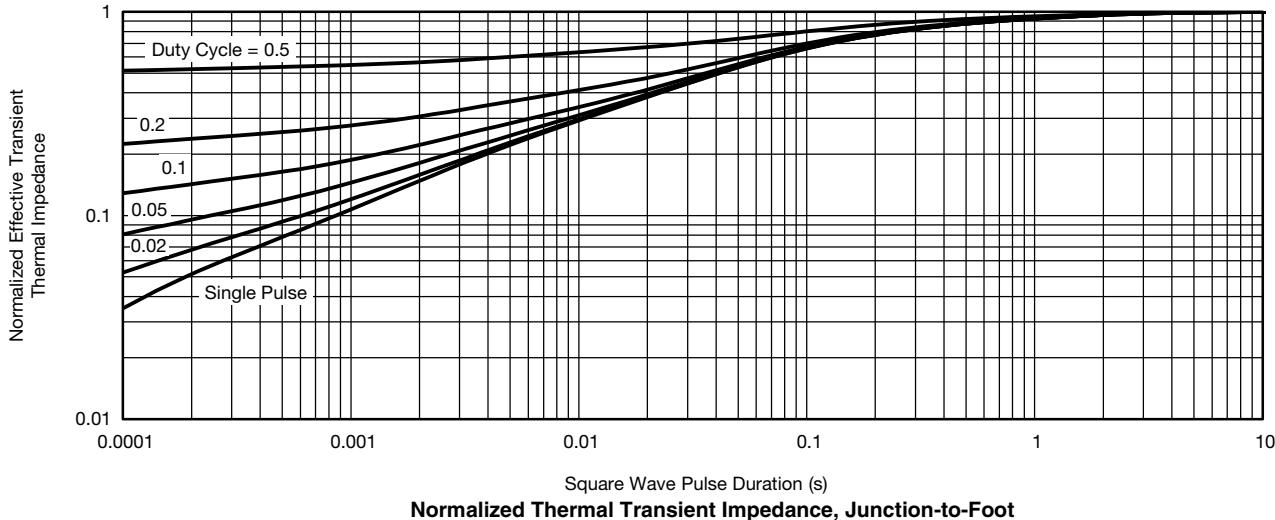
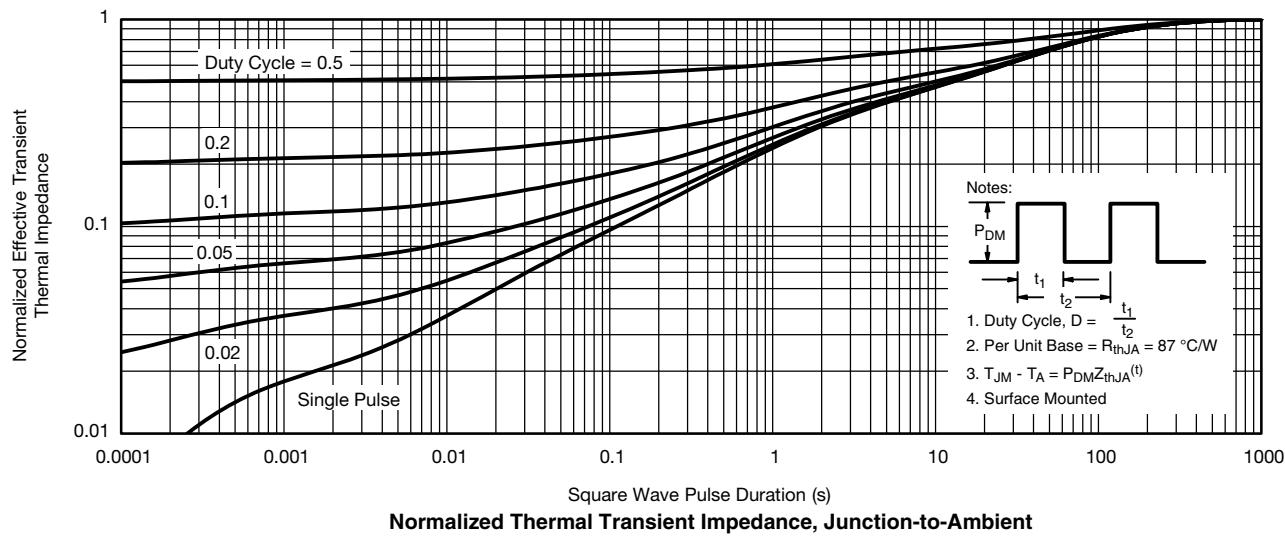
 $T_C$  - Case Temperature (°C)

Power Derating, Junction-to-Foot

 $T_A$  - Ambient Temperature (°C)

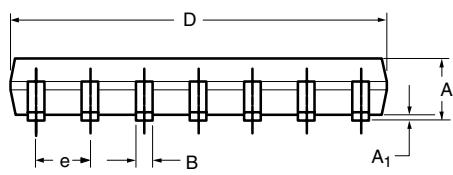
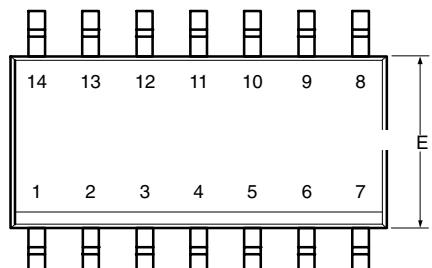
Power Derating, Junction-to-Ambient

\* The power dissipation  $P_D$  is based on  $T_{J(\max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

**CHANNEL-2 TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)


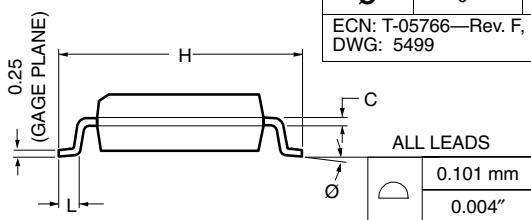
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### SOIC (NARROW): 14-LEAD



Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
<b>A</b>	1.35	1.75	0.053	0.069
<b>A<sub>1</sub></b>	0.10	0.20	0.004	0.008
<b>B</b>	0.38	0.51	0.015	0.020
<b>C</b>	0.18	0.23	0.007	0.009
<b>D</b>	8.55	8.75	0.336	0.344
<b>E</b>	3.8	4.00	0.149	0.157
<b>e</b>	1.27 BSC		0.050 BSC	
<b>H</b>	5.80	6.20	0.228	0.244
<b>L</b>	0.50	0.93	0.020	0.037
<b>Ø</b>	0°	8°	0°	8°

ECN: T-05766—Rev. F, 19-Sep-05  
DWG: 5499



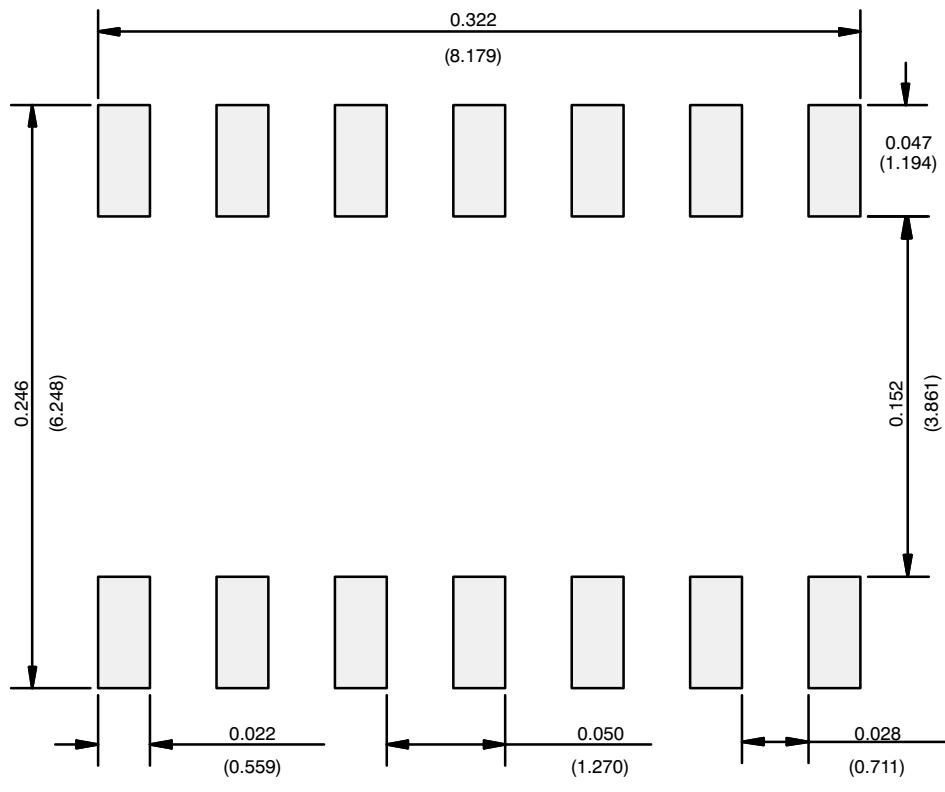


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**RECOMMENDED MINIMUM PADS FOR SO-14**

Recommended Minimum Pads  
Dimensions in Inches/(mm)

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